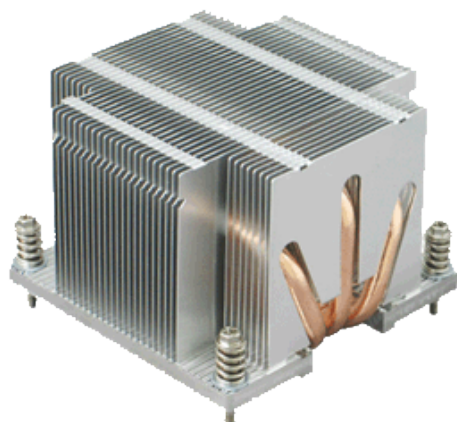




HEL-00020-N1-GP



Application

LGA 2011 (Socket R Square) M4

Test result:

	95W	130W
Flow (CFM)	Rca (°C/W)	Rca (°C/W)
8	0.3091	0.3271
10	0.2892	0.2867
12	0.2617	0.2636
15	0.237	0.2368
16	0.2344	0.2325
20	0.2133	0.2114
25	0.1979	0.1952
30	0.188	0.1855

Safety



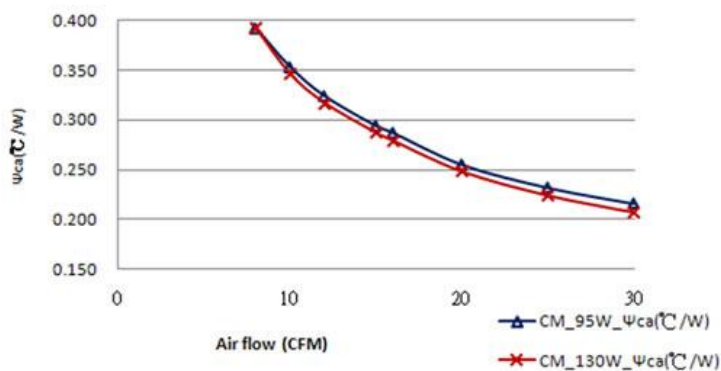
Thermal and Mechanical Spec

Thermal performance for 95W/130W CPU

HSK Assembly Weight: 339 g

CPU Loading: 65 lbf

Performance Curve



Component Specifications

Application System 2U Form Factor Passive Solution

Material Aluminum Fin + Aluminum Base + Heat pipe Diameter 6 × 3

Dimension 88.9L × 88.9W × 63H mm

Fin Thick=0.3mm, Pitch=2.3mm, 68 fin (Solder Free)

Thermal interface Material Shin Etsu 7783 (35 × 35 mm)

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.